

1x4Mx32bit DRAM Card
2x4Mx32bit DRAM Card
1x4Mx36bit DRAM Card
2x4Mx36bit DRAM Card

MF116M-L17ATXX
MF132M-L17ATXX
MF116M-L27ATXX
MF132M-L27ATXX

Connector Type

Two-piece 88-pin

DESCRIPTION

These DRAM CARDS are developed based on JEIDA DRAM CARD GUIDELINE Ver. 2.0.

These cards are made using industry standard 4 M × 4 and 4 M × 1 Dynamic RAM and interface IC's in TSOP.

FEATURES

- All inputs except RAS inputs are buffered.
- Standard card size : 54mm (W) × 85.6mm (L) × 3.3mm (T)
- 88pin 2 piece connector type.
- RAS only refresh mode, CAS before RAS refresh mode and Page mode functions are available.
- Extended refresh is available. (128ms/2048cycle)

APPLICATIONS

Main/expansion memory unit for Personal Computer, Laser-Printer, FAX etc.

PRODUCT LIST

Product No.	Item Type name	Memory capacity	Data Bus width (bits)	Access time (tRAC) (ns)	Connector type	Number of pins	Outline drawing
No. 1	MF116M-L17ATXX	16MB	32	70	Two-piece	88	88P-001
No. 2	MF132M-L17ATXX	32MB	(without parity)				
No. 3	MF116M-L27ATXX	16MB	36				
No. 4	MF132M-L27ATXX	32MB	(with parity)				

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DYNAMIC RAM CARDS

PIN ASSIGNMENT

Pin No.	Symbol	Function	Pin No.	Symbol	Function
1	GND	Ground	45	GND	Ground
2	DQ 0	Data I/O	46	DQ18	Data I/O
3	DQ 1		47	DQ19	
4	DQ 2		48	DQ20	
5	DQ 3		49	DQ21	
6	DQ 4		50	DQ22	
7	DQ 5		51	DQ23	
8	DQ 6		52	DQ24	
9	Vcc		Power supply voltage	53	
10	DQ7	Data I/O	54	DQ26	
11	NC	No connection	55	NC	No connection
12	DQ 8	Data I/O (NC for No. 1, No. 2)	56	GND	Ground
13	A 0	Address input	57	A 1	Address input
14	A 2		58	A 3	
15	Vcc	Power supply voltage	59	A 5	
16	A 4	Address input	60	A 7	
17	NC	No connection	61	A 9	No connection
18	A 6	Address input	62	NC	
19	A 8		63	GND	Ground
20	A10		64	NC	No connection
21	NC	No connection	65	RAS1	Row address strobe 1 (NC for No. 1, No. 3)
22	RAS0	Row address strobe 0	66	CAS2	Column address strobe 2
23	CAS0	Column address strobe 0	67	GND	Ground
24	CAS1	Column address strobe 1	68	CAS3	Column address strobe 3
25	NC	No connection	69	RAS3	Row address strobe 3 (NC for No. 1, No. 3)
26	RAS2	Row address strobe 2	70	WE	Write enable
27	Vcc	Power supply voltage	71	PD 1	Presence detect 1
28	PD 2	Presence detect 2	72	PD 3	Presence detect 3
29	PD 4	Presence detect 4	73	GND	Ground
30	PD 6	Presence detect 6	74	PD 5	Presence detect 5
31	NC	No connection	75	PD 7	Presence detect 7
32	NC		76	PD 8	Presence detect 8
33	DQ17	Data I/O (NC for No. 1, No. 2)	77	NC	No connection
34	DQ 9	Data I/O	78	PD 9	Presence detect 9
35	NC	No connection	79	DQ35	Data I/O (NC for No. 1, No. 2)
36	DQ10	Data I/O	80	DQ27	Data I/O
37	Vcc	Power supply voltage	81	DQ28	
38	DQ11	Data I/O	82	DQ29	
39	DQ12		83	DQ30	
40	DQ13		84	DQ31	
41	DQ14		85	DQ32	
42	DQ15		86	DQ33	
43	DQ16		87	DQ34	
44	GND		Ground	88	GND

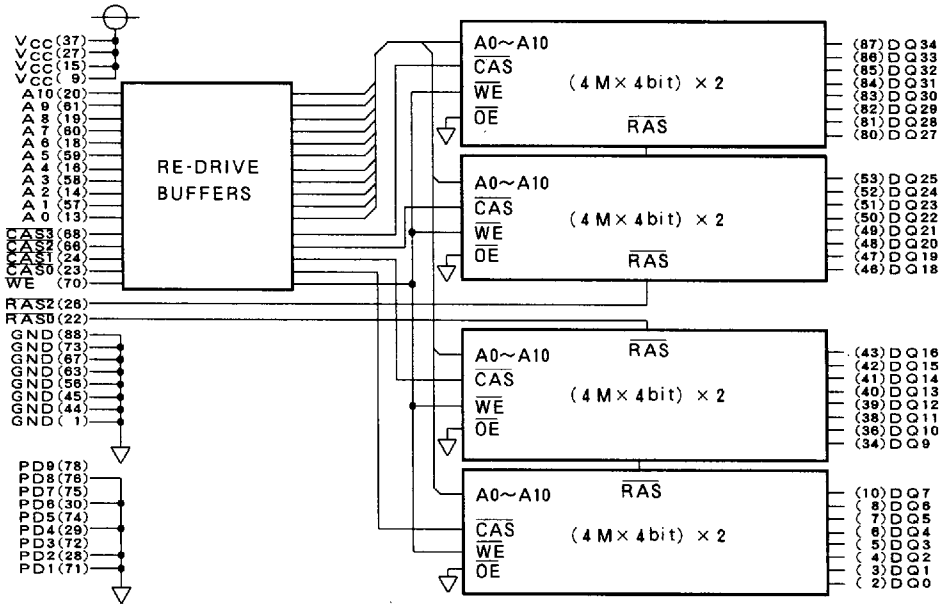
PD Pin Table

Product No.	PD 1	PD 2	PD 3	PD 4	PD 5	PD 6	PD 7	PD 8	PD 9
No. 1	GND	GND	NC	GND	NC	GND	NC	GND	NC
No. 2	GND	GND	NC	GND	GND	GND	NC	GND	NC
No. 3	GND	GND	NC	GND	NC	GND	NC	GND	NC
No. 4	GND	GND	NC	GND	GND	GND	NC	GND	NC

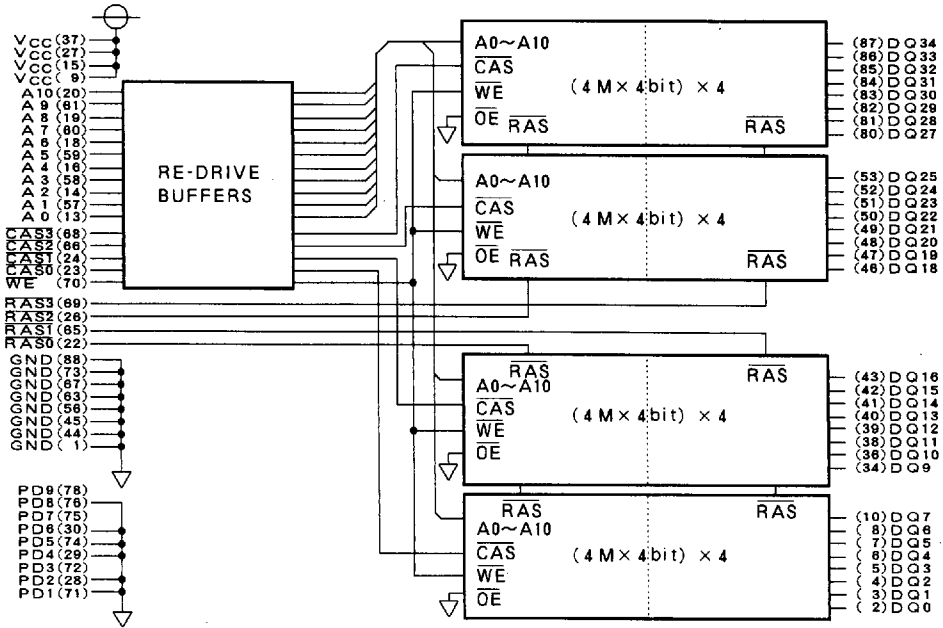
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DYNAMIC RAM CARDS

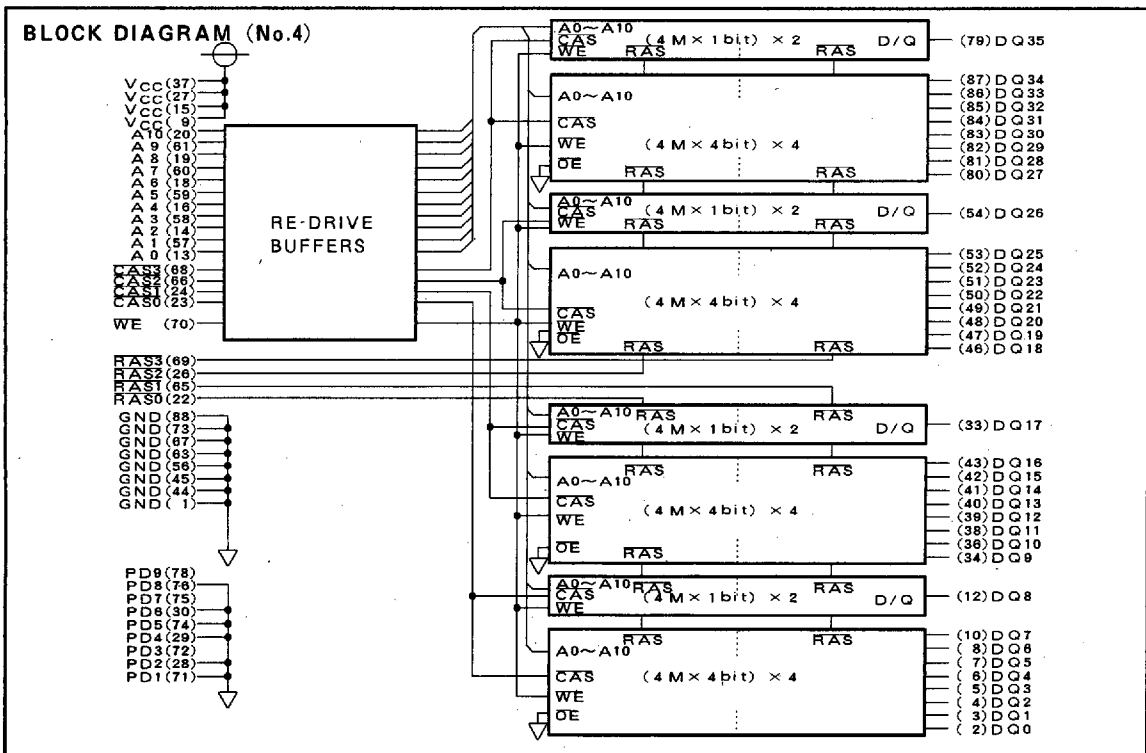
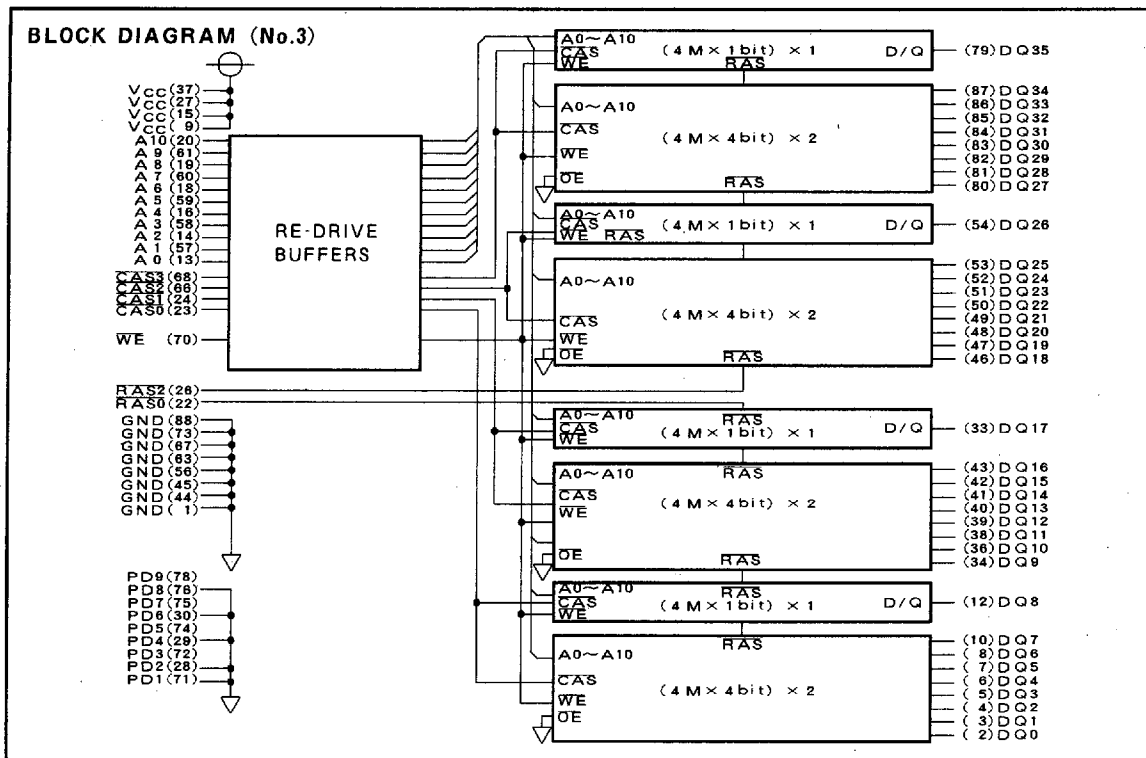
BLOCK DIAGRAM (No.1)



BLOCK DIAGRAM (No.2)



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DYNAMIC RAM CARDS

FUNCTION TABLE

Operation	input					input/output		Refresh	Note
	RAS	CAS	WE	Row Address	Column Address	input	output		
Read	ACT	ACT	NAC	APD	APD	OPN	VLD	YES	Page mode identical
Early write	ACT	ACT	ACT	APD	APD	VLD	OPN	YES	
RAS only refresh	ACT	NAC	DNC	APD	DNC	DNC	OPN	YES	
CAS before RAS refresh	ACT	ACT	NAC	DNC	DNC	DNC	OPN	YES	
Self refresh	ACT	ACT	NAC	DNC	DNC	DNC	OPN	YES	
Standby	NAC	DNC	DNC	DNC	DNC	DNC	OPN	NO	

Note 1 : ACT : active, NAC : nonactive, DNC : don't care, VLD : valid, APD : applied, OPN : open
 Don't be active the even and odd No. RASs at the same time. (Read/Early write cycle only)

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Conditions	Ratings				Unit
			No. 1	No. 2	No. 3	No. 4	
V _{CC}	Supply voltage	With respect to GND	-1.0~7.0				V
V _I	Input voltage		-1.0~7.0				V
V _O	Output voltage		-1.0~7.0				V
I _O	Output current		50				mA
P _d	Power dissipation	T _a =25°C	8	16	12	24	W
T _{opr}	Operating temperature		0~55				°C
T _{stg}	Storage temperature		-40~80				°C

RECOMMENDED OPERATING CONDITIONS (T_a = 0 ~55°C, unless otherwise noted): (Note 2)

Symbol	Parameter	Limits			Unit
		Min.	Typ.	Max.	
V _{CC}	Supply voltage	4.75	5	5.25	V
GND	Supply voltage	0	0	0	V
V _{IH}	High input voltage	0.7 × V _{CC}		V _{CC}	V
V _{IL}	Low input voltage	0		0.8	V

Note 2 : With respect to GND

DYNAMIC RAM CARDS

ELECTRICAL CHARACTERISTICS ($T_a = 0 \sim 55^\circ\text{C}$, $V_{CC} = 5\text{V} \pm 5\%$, $\text{GND} = 0\text{V}$): (Note 3)

Symbol	Parameter	Test condition	Limits								Unit	
			Min.				Typ.	Max.				
			No. 1	No. 2	No. 3	No. 4		No. 1	No. 2	No. 3		No. 4
V_{OH}	High output voltage	$I_{OH} = -5\text{mA}$	2.4					V_{CC}				V
V_{OL}	Low output voltage	$I_{OL} = 4.2\text{mA}$	0					0.4				V
I_{OZ}	Off-stage output current	$0\text{V} \leq V_{OUT} \leq V_{CC}$	-10	-20	-10	-20		10	20	10	20	μA
I_I	Input current	$0\text{V} \leq V_{IN} \leq V_{CC}$ Other input pins = 0V	-40		-60			40		60		μA
$I_{CC1(AV)}$	Average supply current from V_{CC} , operating (Note 4, 5, 6)	$\overline{\text{RAS}}$, $\overline{\text{CAS}}$ cycling $\text{trc} = \text{twc} = \text{min}$, output open						900	920	1250	1280	mA
$I_{CC2(AV)}$	Supply current from V_{CC} , standby (Note 7)	$\overline{\text{RAS}} = \overline{\text{CAS}} \geq V_{CC} - 0.2\text{V}$, other input pins $\geq V_{CC} - 0.2\text{V}$ or $\leq 0.2\text{V}$, output open						3.2	6.4	3.6	7.2	mA
$I_{CC3(AV)}$	Average supply current from V_{CC} , refreshing (Note 4, 6)	$\overline{\text{RAS}}$ cycling, $\overline{\text{CAS}} = V_{IH}$ $\text{trc} = \text{min}$, output open						890	1750	1240	2450	mA
$I_{CC4(AV)}$	Average supply current from V_{CC} , Page-Mode (Note 4, 5, 6)	$\overline{\text{RAS}} = V_{IL}$, $\overline{\text{CAS}}$ cycling $\text{trc} = \text{min}$, output open						530	580	890	970	mA
$I_{CC6(AV)}$	Average supply current from V_{CC} , $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ refresh mode (Note 4, 6)	$\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ refresh cycling $\text{trc} = \text{min}$, output open						850	1700	1160	2300	mA
$I_{CC8(AV)}$	Average supply current from V_{CC} , Extended refresh mode (Note 7)	$\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ refresh cycling $\text{WE} \geq V_{CC} - 0.2\text{V}$ other input pins $\geq V_{CC} - 0.2\text{V}$ or $\leq 0.2\text{V}$, output open $\text{trc} = 62.5\mu\text{s}$						5	10	5.7	11.4	mA
$I_{CC9(AV)}$	Average supply current from V_{CC} , Self refresh mode (Note 7)	$\overline{\text{RAS}} = \overline{\text{CAS}} \leq 0.2\text{V}$, $\text{WE} \geq V_{CC} - 0.2\text{V}$ output open						5	10	5.7	11.4	mA

Note 3 : Current flowing into a CARD is positive, out is negative.

4 : $I_{CC1(AV)}$, $I_{CC3(AV)}$, $I_{CC4(AV)}$ and $I_{CC6(AV)}$ are dependent on cycle rate.

Specified values are obtained at the fastest cycle rate.

5 : $I_{CC1(AV)}$ and $I_{CC4(AV)}$ are dependent on output loading.

Specified values are obtained with the outputs open.

6 : Column Address can be changed once or less while $\overline{\text{RAS}} = V_{IL}$ and $\overline{\text{CAS}} = V_{IH}$.

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SWITCHING CHARACTERISTICS ($T_a = 0 \sim 55^\circ\text{C}$, $V_{CC} = 5\text{V} \pm 5\%$, $GND = 0\text{V}$): (Note7)

Symbol	Parameter	Limits		Unit
		Min.	Max.	
t _{CAC}	Access time from $\overline{\text{CAS}}$ (Note 8, 9)		27	ns
t _{RAC}	Access time from $\overline{\text{RAS}}$ (Note 8, 10)		70	ns
t _{CAA}	Column Address access time (Note 8, 11)		42	ns
t _{OFF}	Output disable time after $\overline{\text{CAS}}$ high (Note12)	0	27	ns

Note 7 : An initial pause of 500 μ sec is required after power-up followed by any 8 $\overline{\text{RAS}}$ or $\overline{\text{RAS}}/\overline{\text{CAS}}$ cycles before proper device operation is achieved. Note that $\overline{\text{RAS}}$ may be cycled during the initial pause. And any 8 $\overline{\text{RAS}}$ or $\overline{\text{RAS}}/\overline{\text{CAS}}$ cycles are required after prolonged periods of $\overline{\text{RAS}}$ inactivity before proper device operation is achieved.

8 : Measured with a load circuit equivalent to 2 TTL loads and 100pF.

9 : Assume that $t_{\text{RCD}} \geq t_{\text{RCD(max)}}$ and $t_{\text{ASC}} \geq t_{\text{ASC(max)}}$.

10 : Assume that $t_{\text{RCD}} \leq t_{\text{RCD(max)}}$ and $t_{\text{RAD}} \leq t_{\text{RAD(max)}}$.

11 : Assume that $t_{\text{RAD}} \geq t_{\text{RAD(max)}}$ and $t_{\text{ASC}} \leq t_{\text{ASC(max)}}$.

12 : t_{OFF(max)} define the time at which the output achieves the high impedance state ($|I| \leq 10\ \mu\text{A}$ or $20\ \mu\text{A}$) and are not reference to $V_{\text{OH(min)}}$ or $V_{\text{OL(max)}}$.

TIMING REQUIREMENTS ($T_a = 0 \sim 55^\circ\text{C}$, $V_{CC} = 5\text{V} \pm 5\%$, $GND = 0\text{V}$): (Note 13, 14)

Symbol	Parameter	Limits		Unit
		Min.	Max.	
t _{REF}	Refresh cycle time		32	ms
t _{REF}	Refresh cycle time ($\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ refresh cycling)		128	ms
t _{RP}	$\overline{\text{RAS}}$ high pulse width	50		ns
t _{RCD}	Delay time, $\overline{\text{RAS}}$ low to $\overline{\text{CAS}}$ low (Note15)	20	43	ns
t _{CRP}	Delay time, $\overline{\text{CAS}}$ high to $\overline{\text{RAS}}$ low (Note16)	17		ns
t _{RPC}	Precharge to $\overline{\text{CAS}}$ active time.	0		ns
t _{CPN}	$\overline{\text{CAS}}$ high pulse width	10		ns
t _{RAD}	Column address delay time from $\overline{\text{RAS}}$ low (Note 17)	17	28	ns
t _{ASR}	Row address setup time before $\overline{\text{RAS}}$ low	10		ns
t _{ASC}	Column address setup time before $\overline{\text{CAS}}$ low (Note18)	5	10	ns
t _{RAH}	Row address hold time after $\overline{\text{RAS}}$ low	10		ns
t _{CAH}	Column address hold time after $\overline{\text{CAS}}$ low	15		ns
t _T	Transition time (Note19)	3	50	ns

Note 13 : The timing requirements are assumed $t_T = 5\text{ns}$.

14 : $V_{\text{IH(min)}}$ and $V_{\text{IL(max)}}$ are reference levels for measuring timing of input signals.

15 : t_{RCD(max)} is specified as a reference point only.

If $t_{\text{RCD}} \geq t_{\text{RCD(max)}}$, access time is defined as t_{CAC} and t_{CAA}.

16 : t_{CRP} requirement is applicable for all $\overline{\text{RAS}}/\overline{\text{CAS}}$ cycles.

17 : t_{RAD(max)} is specified as a reference point only.

If $t_{\text{RAD}} \geq t_{\text{RAD(max)}}$ and $t_{\text{ASC}} \leq t_{\text{ASC(max)}}$, access time is assumed by t_{CAA} for read cycle.

18 : t_{ASC(max)} is specified as a reference point only of address access time.

19 : t_T is measured between $V_{\text{IH(min)}}$ and $V_{\text{IL(max)}}$.

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Read and Refresh Cycles

Symbol	Parameter	Limits		Unit
		Min.	Max.	
tRC	Read cycle time	130		ns
tRAS	RAS low pulse width	70	10000	ns
tCAS	CAS low pulse width	20	10000	ns
tCSH	CAS hold time after RAS low	70		ns
tRSH	RAS hold time after CAS low	27		ns
tRSC	Read setup time before CAS low	5		ns
tRCH	Read hold time after CAS high	0		ns
tRRH	Read hold time after RAS high	10		ns

Write Cycle (Early Write)

Symbol	Parameter	Limits		Unit
		Min.	Max.	
tWC	Write cycle time	130		ns
tRAS	RAS low pulse width	70	10000	ns
tCAS	CAS low pulse width	20	10000	ns
tCSH	CAS hold time after RAS low	70		ns
tRSH	RAS hold time after CAS low	27		ns
twCS	Write setup time before CAS low	5		ns
twCH	Write hold time after CAS low	15		ns
tDS	Data setup time	10		ns
tDH	Data hold time after CAS low	22		ns

Page Mode Cycle (Read, Early Write)

Symbol	Parameter	Limits		Unit
		Min.	Max.	
tPC	Read, Write cycle time	55		ns
tCP	CAS high pulse width	10		ns
tRAS	RAS low pulse width (Note 20)	125	100000	ns

Note 20 : tRAS(min) is specified by the following formula as two cycles of CAS input are executed,
 $tRAS(min) = tCSH(min) + tPC(min)$.

CAS before RAS Refresh Cycle (Note 21)

Symbol	Parameter	Limits		Unit
		Min.	Max.	
tCSR	CAS setup time for CAS before RAS refresh	20		ns
tCHR	CAS hold time for CAS before RAS refresh	15		ns

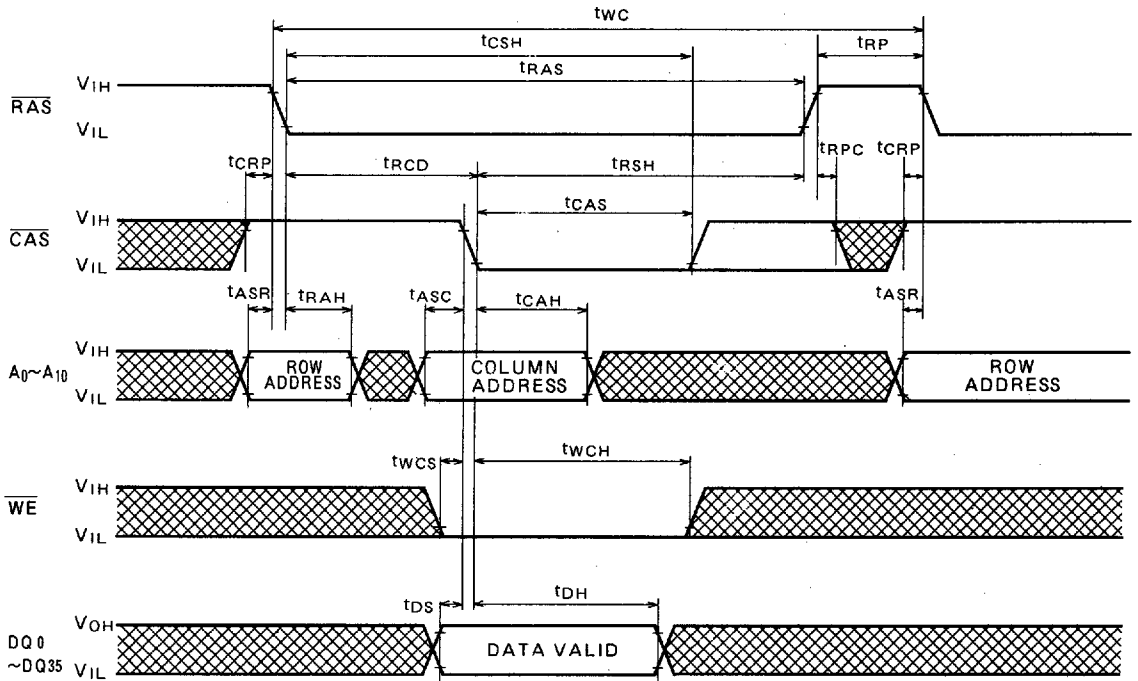
Note 21 : Eight or more CAS before RAS cycles are necessary for proper operation of CAS before RAS refresh mode.

Self Refresh Cycle

Symbol	Parameter	Limits		Unit
		Min.	Max.	
tRASS	RAS low pulse width	100		μs
tRPS	CAS high pulse width	130		ns
tCHS	RAS hold time after RAS high	-50		ns

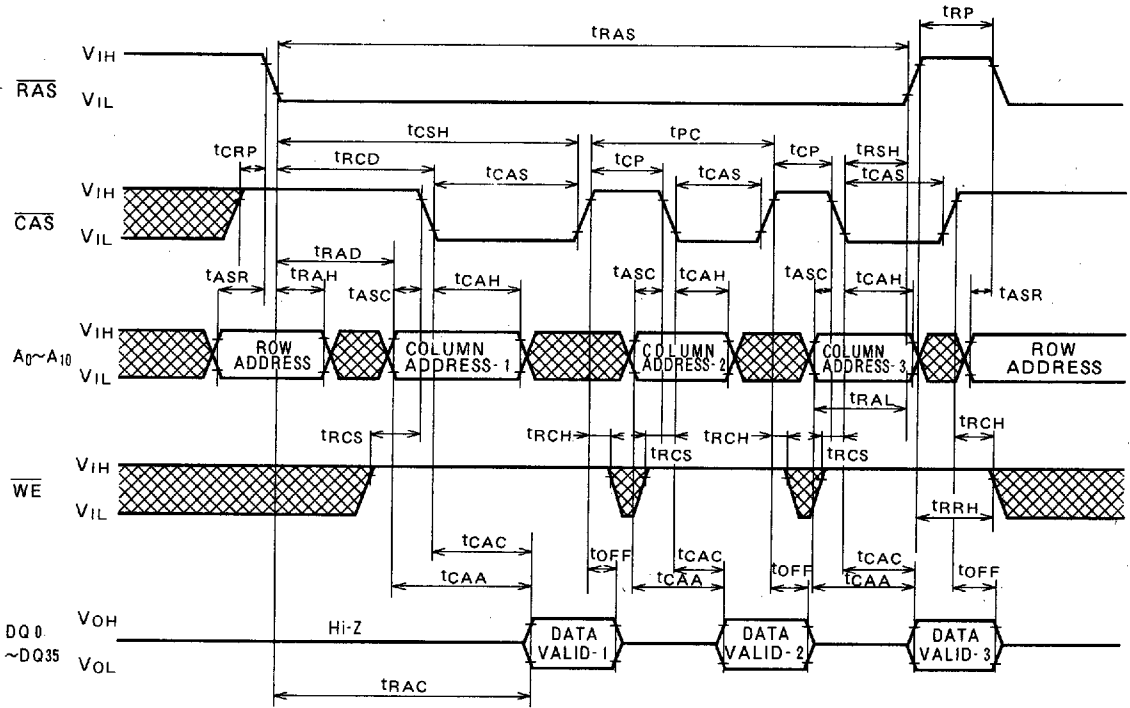
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Early Write Cycle



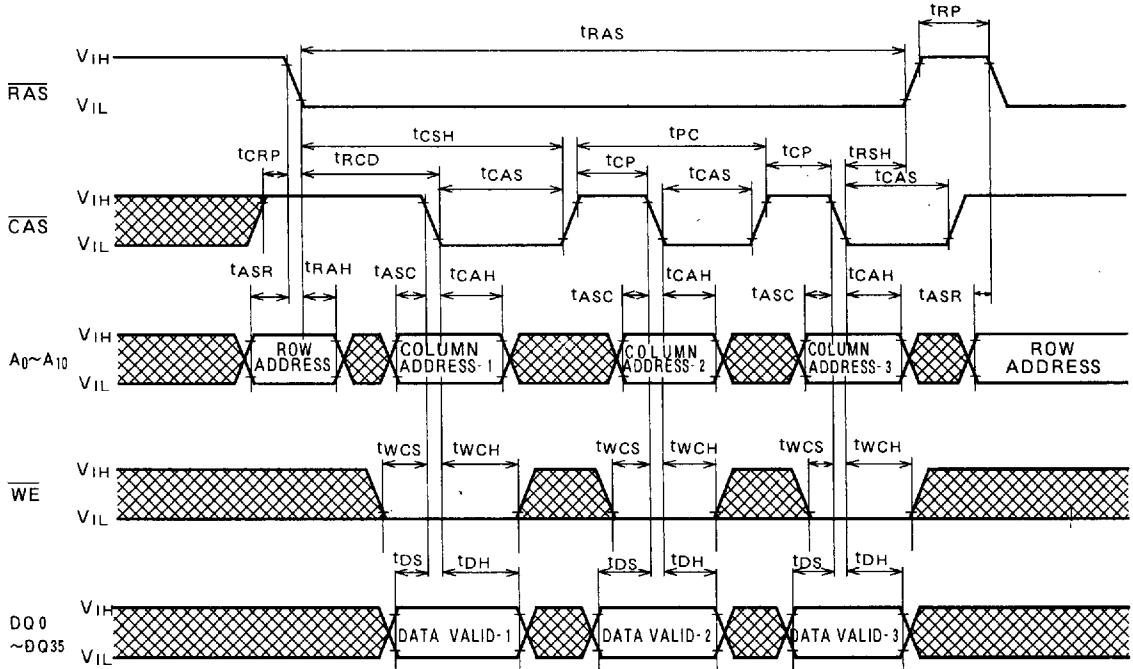
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Page-Mode Read Cycle



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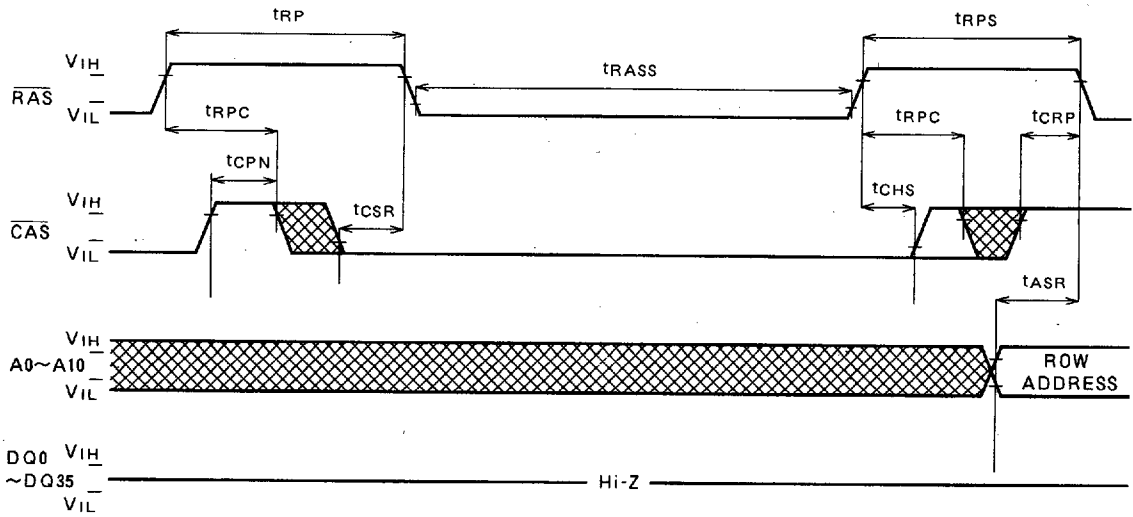
Page-Mode Early Write Cycle



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DYNAMIC RAM CARDS

Self Refresh Cycle (Note 25, 26)



Note 25 : $\overline{WE} = V_{IH}$

Note 26 : SELF REFRESH ENTRY & EXIT CONDITIONS

(1) In case of distributed refresh

The last/first full refresh cycles (2 K) must be made within t_{NS}/t_{SN} before/after self refresh, on the condition of $t_{NS} \leq 32ms$ and $t_{SN} \leq 32ms$.



(2) In case of burst refresh

The last/first full refresh cycles (2 K) must be made within t_{NS}/t_{SN} before/after self refresh, on the condition of $t_{NS} + t_{SN} \leq 32ms$.

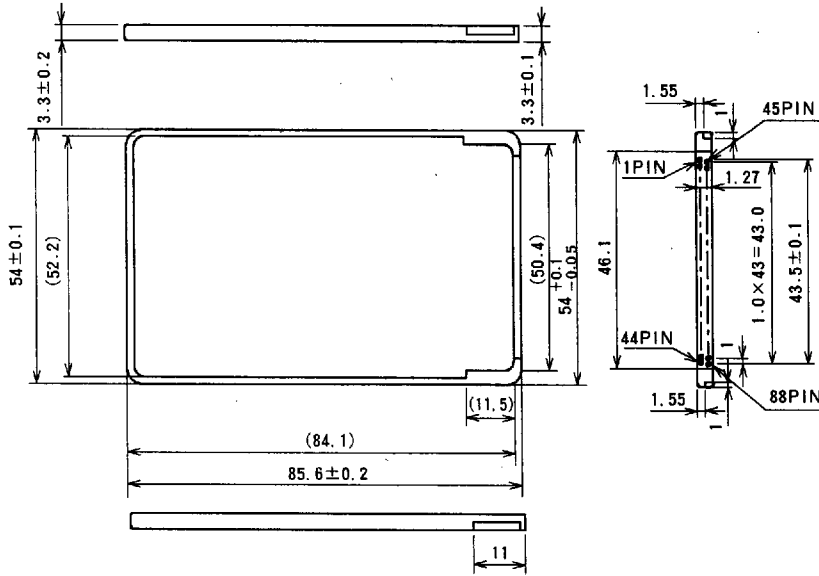


MITSUBISHI MEMORY CARD CARD DIMENSIONS

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TWO - PIECE 88 pin (5V connector keying)

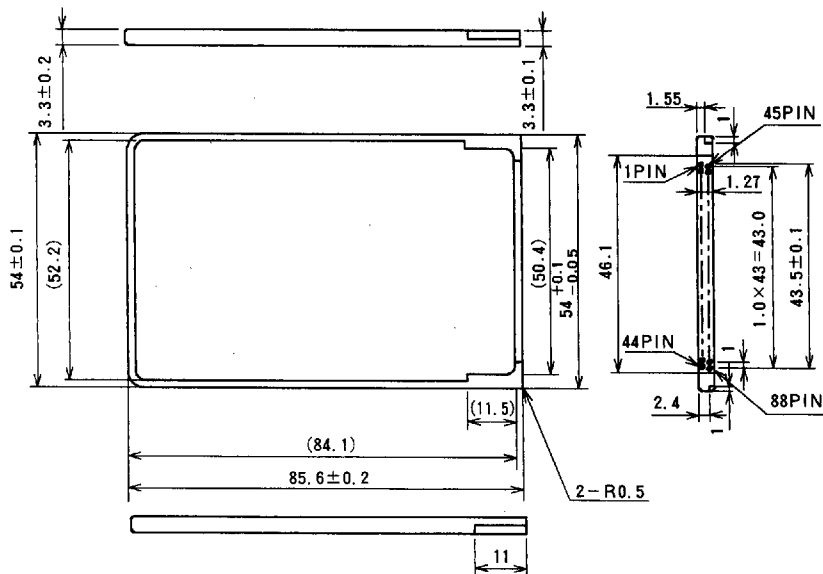
Dimensions in mm



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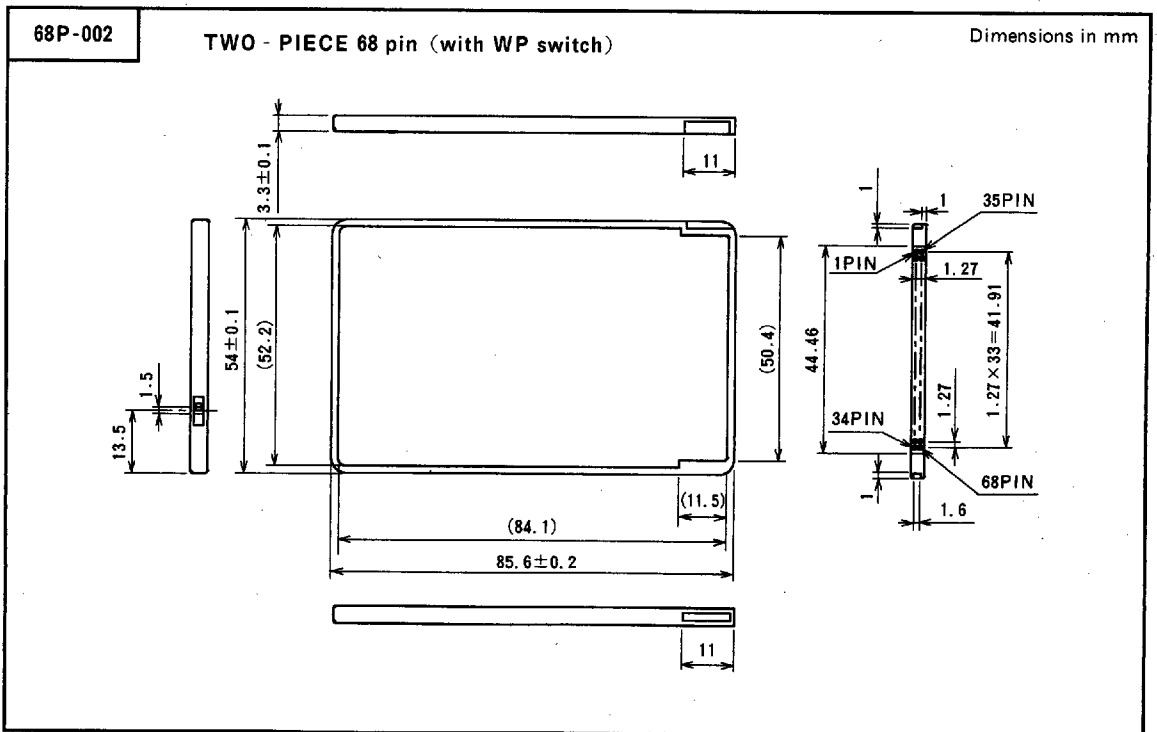
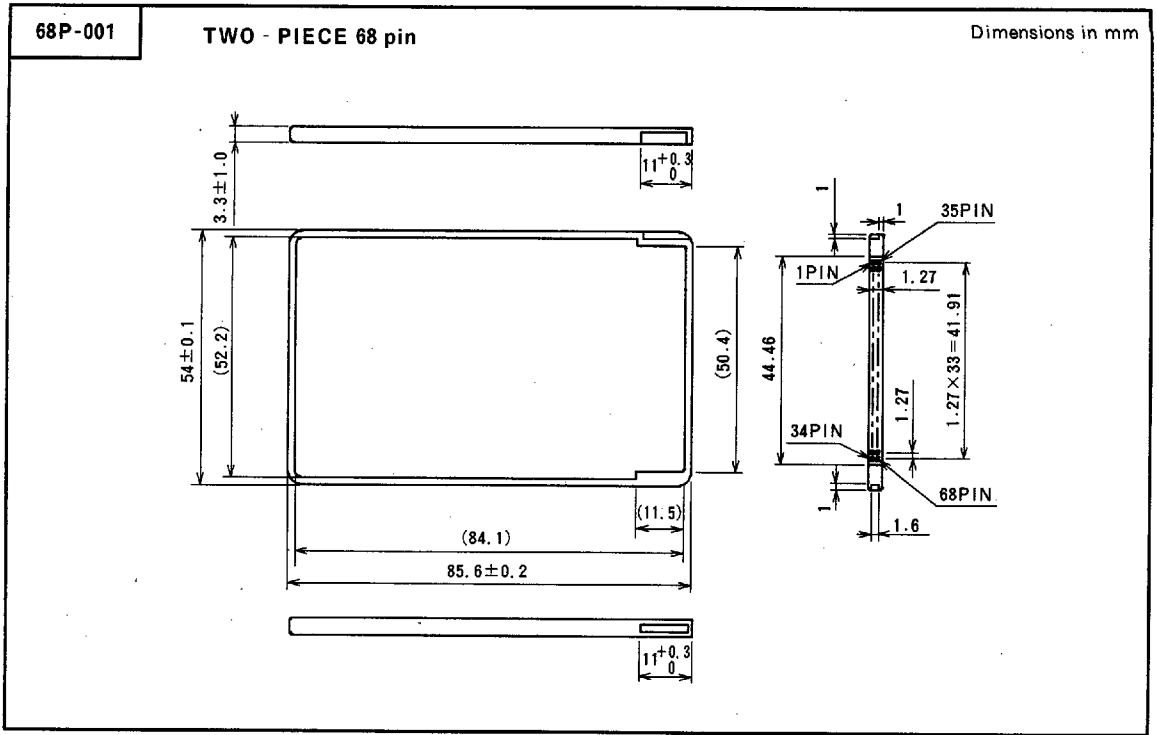
TWO - PIECE 88 pin (3.3V connector keying)

Dimensions in mm



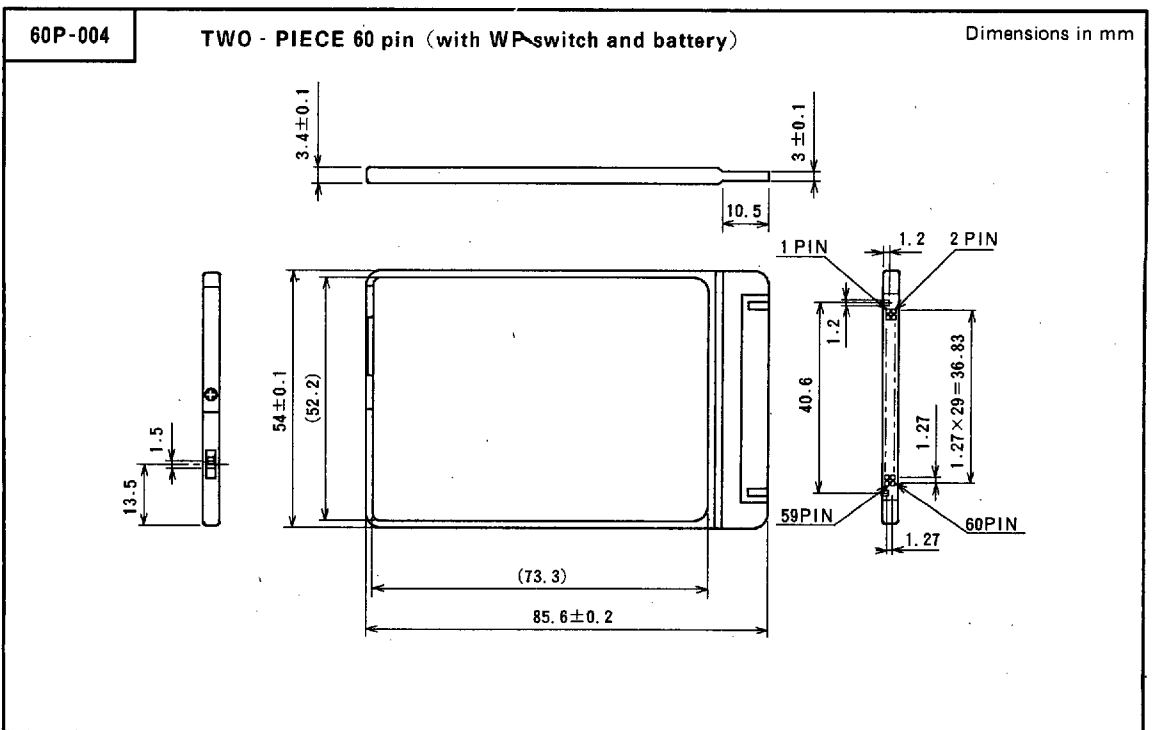
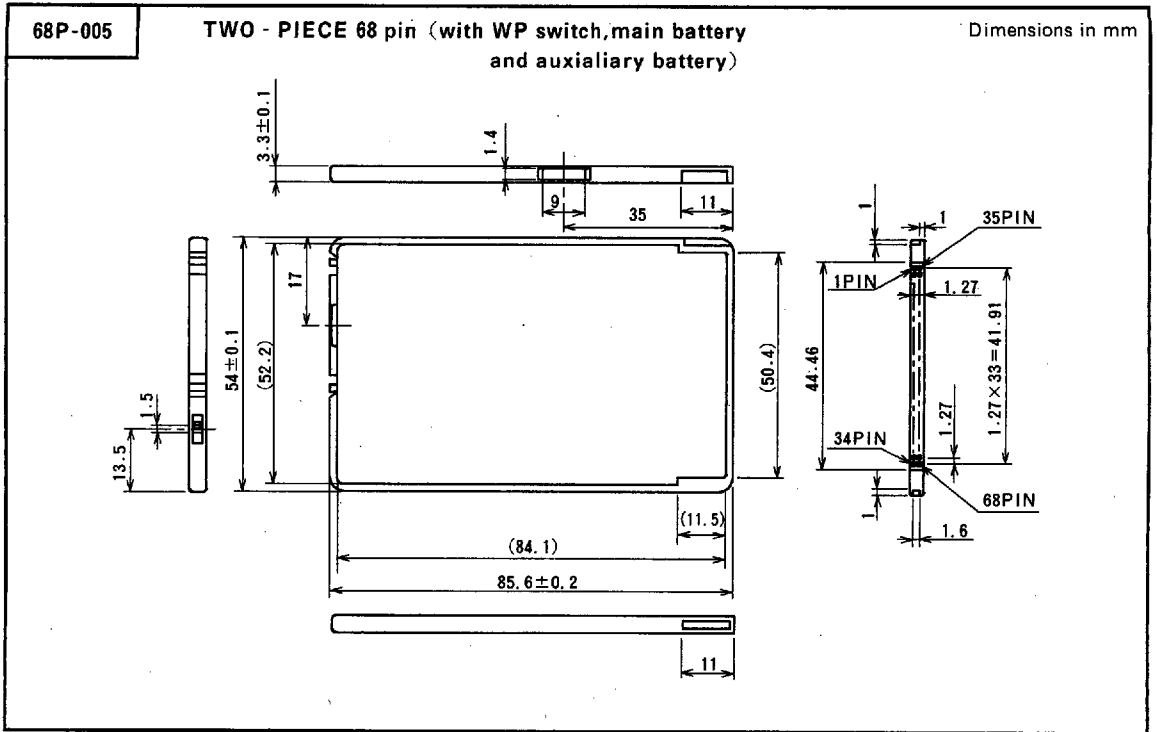
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